

SMD Switching Diode

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CDSU400 (Lead-free Device)

High Speed



Features

Designed for mounting on small surface.

Extremely thin/leadless package.

Low leakage current.

High mounting capability, strong surge withstand, high reliability.

Mechanical data

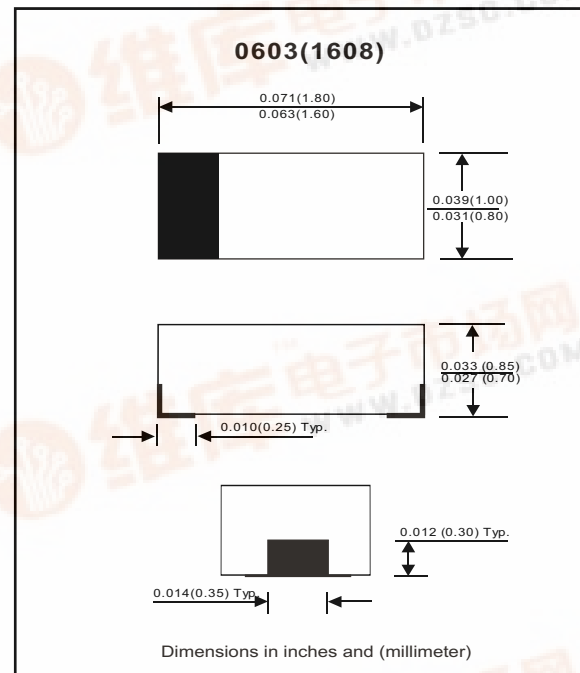
Case: 0603 (1608) standard package, molded plastic.

Terminals: Gold plated, solderable per MIL-STD-750, method 2026.

Polarity: Indicated by cathode band.

Mounting position: Any.

Weight: 0.003 gram (approximately)



Maximum Rating (at TA = 25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Repetitive peak reverse voltage		VRRM			90	V
Reverse voltage		VR			80	V
Average forward current		Io			100	mA
Forward current , surge peak	8.3 ms single half sine-wave superimposed on rate load (JEDEC method)	IFSM		1000		mA
Power Dissipation		Pd			150	mW
Storage temperature		TSTG	-40		+125	°C
Junction temperature		Tj	-40		+125	°C

Electrical Characteristics (at TA = 25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Forward voltage	IF = 100 mADC	VF			1.0	V
Reverse current	VR = 80 V	IR			0.1	uA
Capacitance between terminals	f = 1MHz, and 0.5VDC reverse voltage	CT		3		pF
Reverse recovery time	VR = 6V, IF = 10 mA, RL =50 ohms	Trr		4		nS

RATING AND CHARACTERISTIC CURVES (CDSU400)

Fig. 1 - Forward characteristics

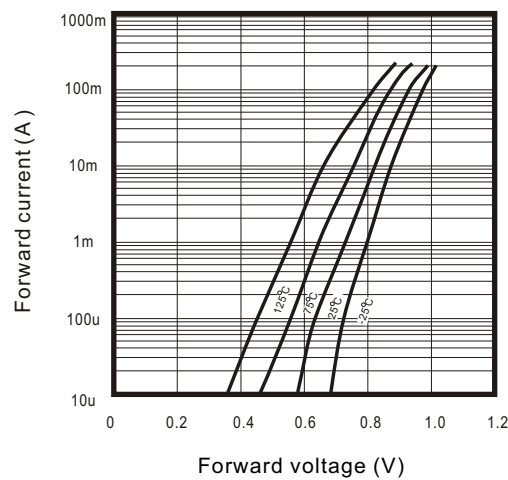


Fig. 2 - Reverse characteristics

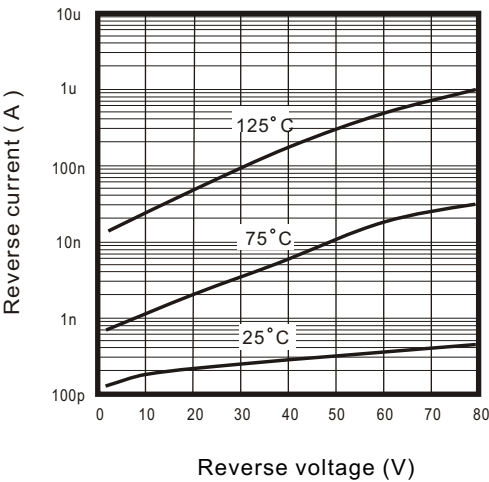


Fig. 3 - Capacitance between terminals characteristics

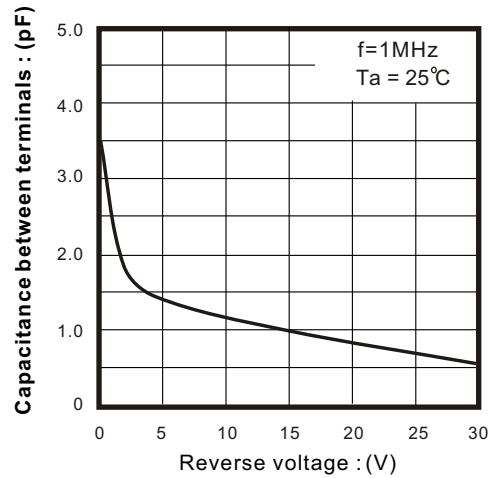


Fig. 4 - Current derating curve

